

/ Descriptions

/ Features

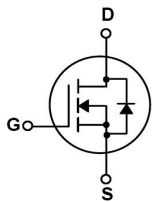
DS

dv/dt

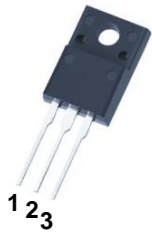
/ Applications

DC/DC

/ Equivalent Circuit

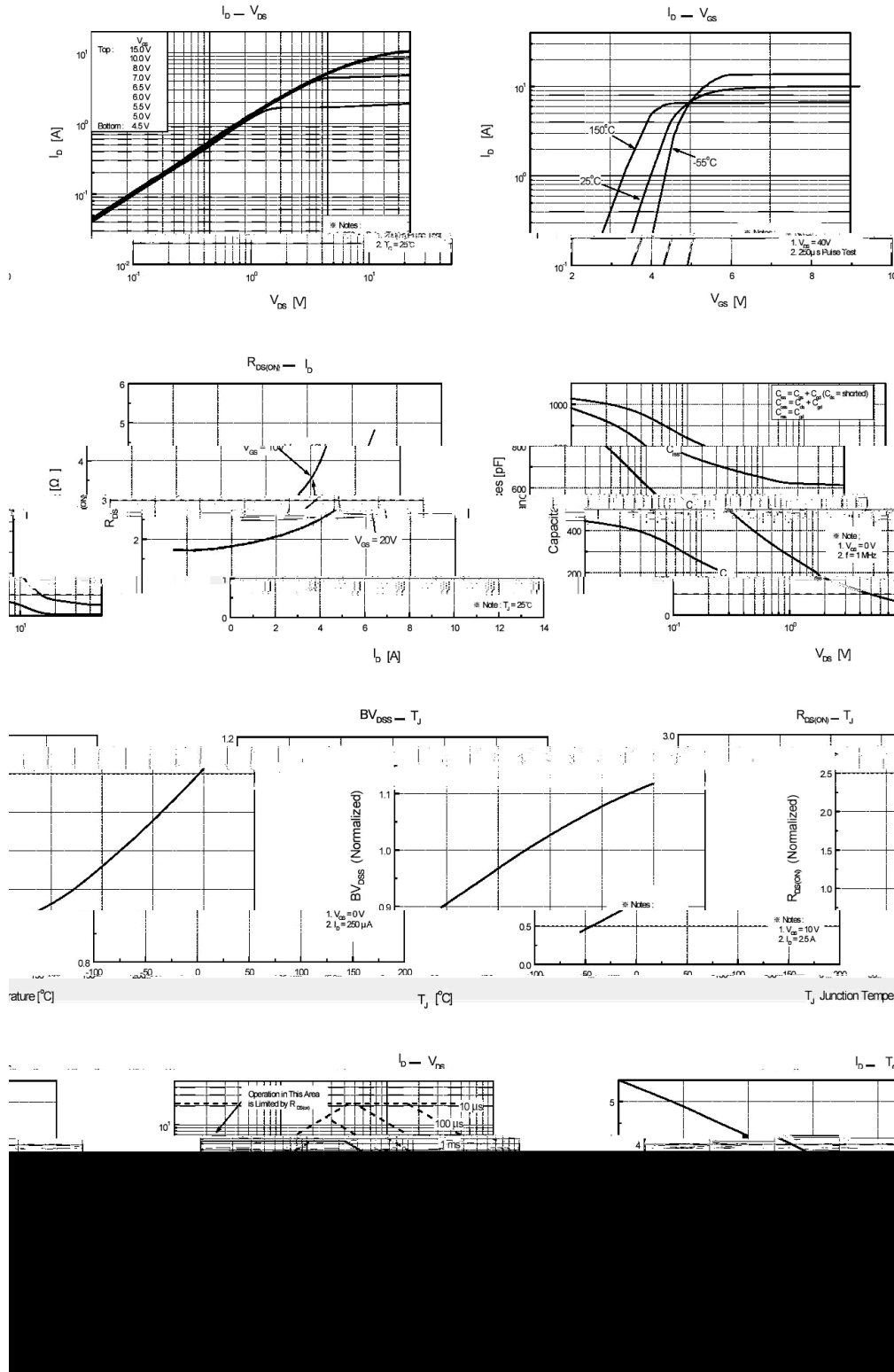


/ Pinning

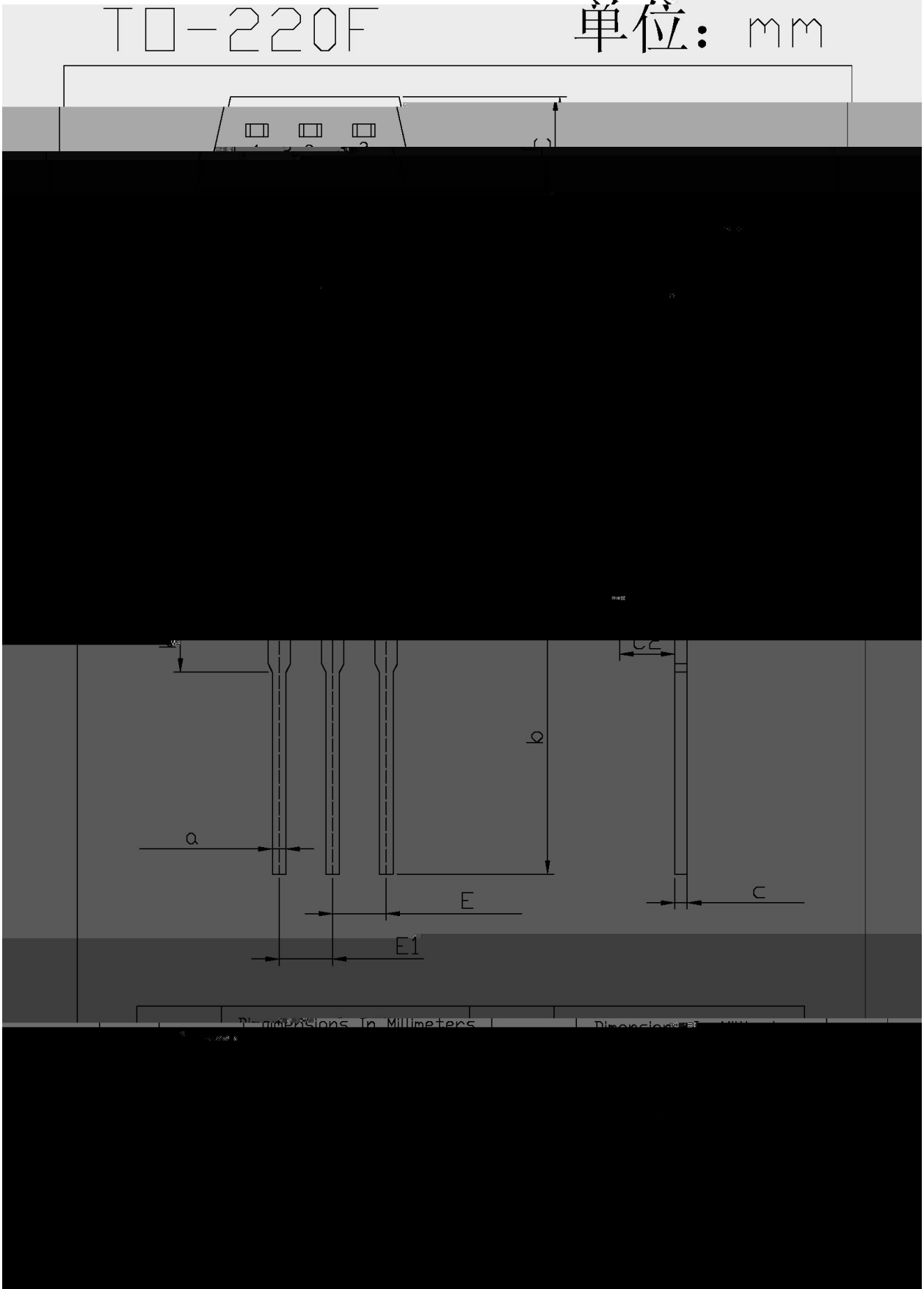


/ h_{FE} Classifications & Marking

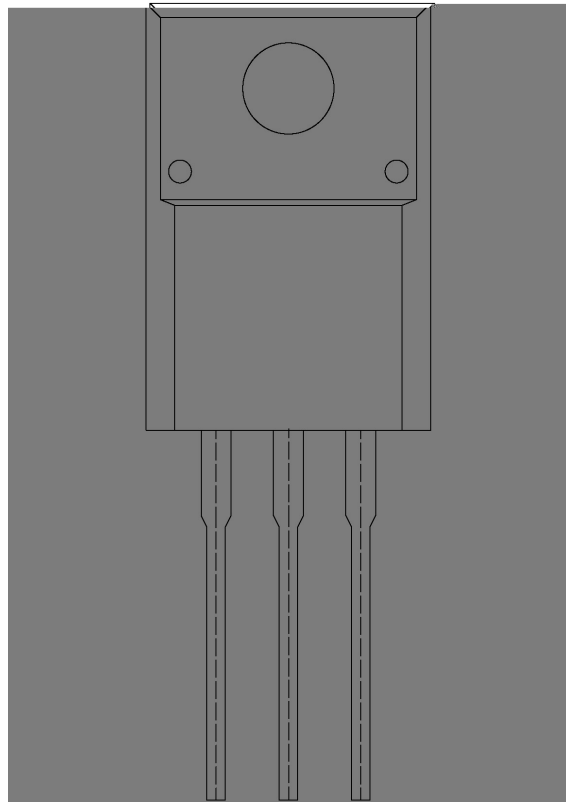
/ Electrical Characteristic Curve



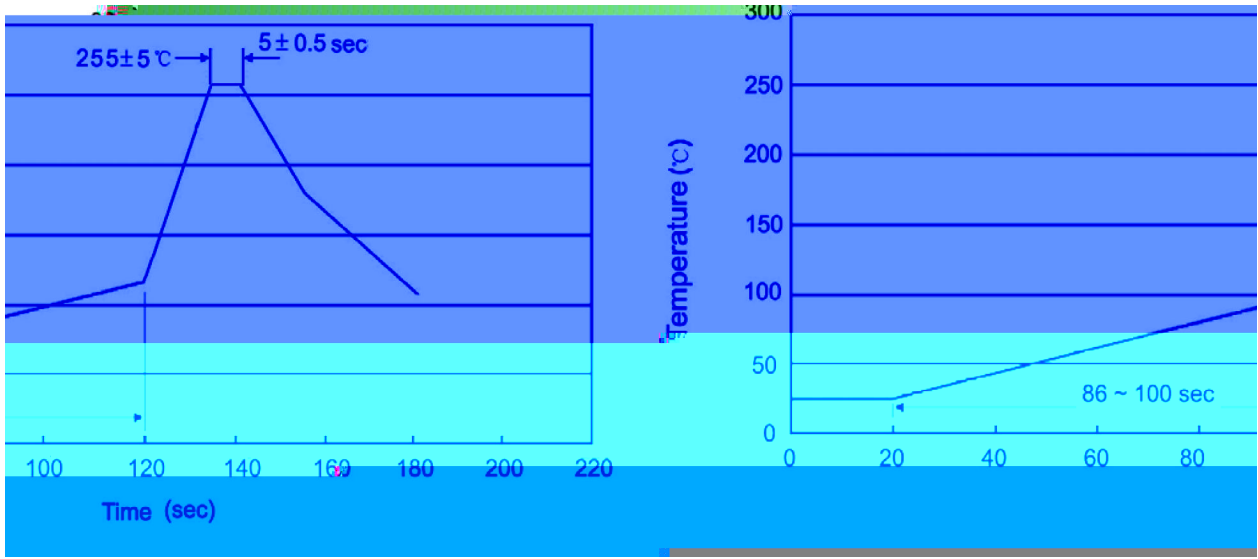
/ Package Dimensions



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



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/ Resistance to Soldering Heat Test Conditions

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/ Packaging SPEC.

封装形式	只袋	袋盒	只盒	包装数量	包装尺寸	:
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